Thermosets

EPOXY MOULDING COMPOUNDS (EMC)

Apart from the gentle incorporation of high additive proportions, the central requirement in the preparation of epoxy resin moulding compounds is to maintain the absolute temperature limit below the cross-linking temperature.

Application

- Sensor electronics
- Electrical engineering
- Automation
- Electromobility
- Drives

Compounding requirements

- Demanding insulation properties
- High resistance to heat, solvent, moisture
- Processing below cross-linking temperature
- Dust-free production
- Wear resistance of equipment
- High filler loading

BUSS Technology

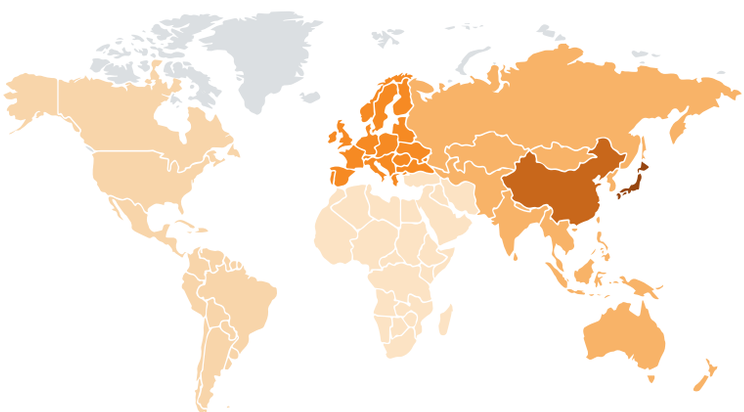
Strengths

- Precise temperature control
- Excellent mixing and homogenizing capabilities
- Effective liquid injection
- Easy and fast opening of kneader for cleaning or emergencies (e.g. power failure)

Benefits

- High production quality and volume
- Excellent product properties
- High product quality
- Low operating cost

BUSS Kneaders for EMC Compounding around the world



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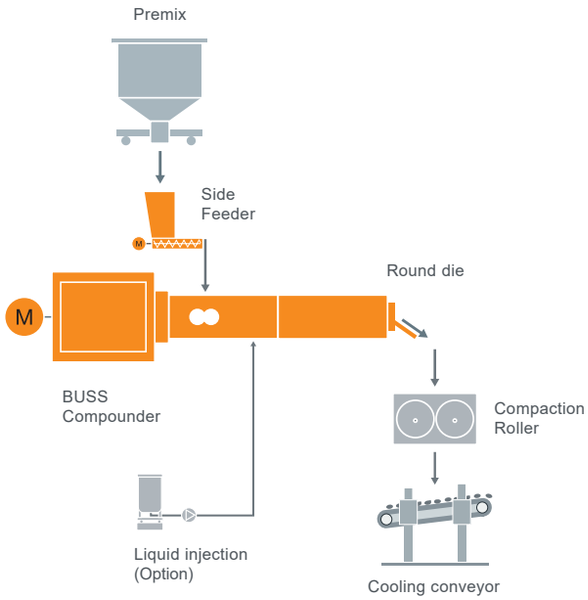
Typical plant layout for EMC



BUSS COMPEO Technical Data

BUSS Compounder[1]	Machine Data				Discharge Unit	Throughput[2]
	Screw diameter [mm]	Process length [L/D]	Screw speed max [rpm]	Drive power max [kW]		Thermosets [kg/h]
COMPEO 55	55	11 or 13	300	25	-	50-150
COMEPO 88	88	11 or 13	300	100	-	200-500
COMPEO 110	110	11 or 13	300	200	-	400-1000
COMPEO 137	137	11 or 13	300	400	-	800-2000
COMPEO 176	176	11 or 13	300	800	-	1600-4000

[1]The compounder is liquid tempered
[2]Expected throughputs depending on raw materials and formulation

More info!
busscorp.com/industries/epoxy-moulding-compounds-emc

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